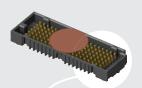


IGH SPEED LOW PROFILE OPEN PIN



LPAM SERIES

(1,27 mm) .050"

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LPAM

Insulator Material: Black LCP
Terminal Material:
Copper Alloy Plating: Au or Šn over 50 μ" (1,27 μm) Ni **Current Rating:** 2.2 A per pin (6 adjacent pins powered) Working Voltage: 250 VA

RoHS Compliant:

Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE

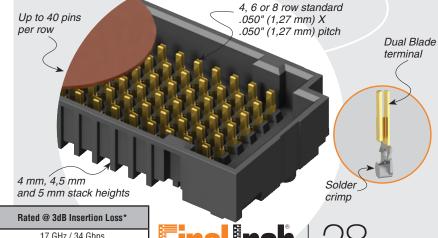
- Other pins/row and
- · Other Gold plating options Contact Samtec.

Mates with:

LPAM/LPAF 4 mm Stack Height

LPAM

Single-Ended Signaling



onigic Ended orginaling	17 d112 / 54 dbp3	
Differential Pair Signaling	18.5 GHz / 37 Gbps	
*Test board losses de-embedded from performance data.		
D (

Performance data for other stack heights and complete test data available at www.samtec.com?LPAM or contact sig@samtec.com

NO. PINS **LEAD PLATING** NO. OF **OPTION PER ROW** STYLE

ROWS

RTIF

SOLDER TYPE

Gbps

(MOQ Required)

- Tin-Lead Solder Charge
- row counts

-10, –20, -30, –40







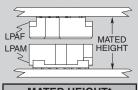
-08=Eight Rows







MATED HEIGHT

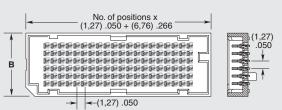


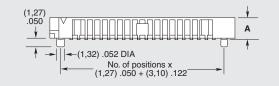
MATED HEIGHT*			
LPAM	LPAF LEAD STYLE		
STYLE	-03.0	-03.5	
-01.0	(4,00) .157	(4,50) .177	
-01.5	(4,50) .177	(5,00) .197	
*Processing conditions will affect mated height.			

Note: Patent Pending

Note: Some sizes, styles and options are non-standard, non-returnable.

NO. OF ROWS	В
-04	(8,18) .322
-06	(10,72) .422
-08	(13,26) .522





LEAD STYLE	Α
-01.0	(3,68) .145
-01.5	(4,19) .165